

iMAPS New England Chapter
International Microelectronics Assembly and Packaging Society

On-Line Registration Now Open—[Reserve Your Spot Today!](#)



Explore the Next Generation of Microelectronics

The 41st Annual iMAPS New England Symposium & Expo

7:30 a.m. to 4:30 p.m., May 6, 2014
(first session starts at 8:30 a.m.)

Holiday Inn Conference Center—Boxborough, MA

Experience “The Next Generation of Microelectronics” at the 41st Annual iMAPS New England Symposium. As the largest regional microelectronics event, iMAPS New England features seven panels with presentations by 36 industry experts discussing today's opportunities and challenges. In addition to hearing from keynote speaker Dr. Timo Lebold of Retina Implant-Germany, attendees can also collaborate with more than 50 exhibitors—demonstrating the latest cost-saving and efficiency-improvement technologies while offering a glimpse of upcoming innovations.

Symposium & Expo Highlights

- **Star Tr^ek Theme:** “The Next Generation of Microelectronics”
- **Keynote Speaker:** Germany's Dr. Timo Lebold of Retina Implant, devices that re-store human vision
- **Comprehensive Technical Program:** 7 Technical Sessions/36 Presenters
- **50+ Exhibitors:** See the latest technologies and preview future innovations
- **Networking Opportunities:** With the best and the brightest of the microelectronics industry
- **Full Poster Session:** Explore creative posters and chat with the authors
- **Student Paper & Poster Competition:** Cash prize for the top submission
- **Employment Center:** Review job opportunities (send openings to John Blum – jblum@gmail.com)
- **RF Microwave Packaging Technology Class:** (Post Conference May 7-9) with TJ Green Associates and iMAPS New England (see link below)
- **Multi-Course Lunch:** To keep you going all day long!
- **Lots of Fun, Games and Prizes!!!**

Session and Presentation Topics

- NANO and MEMS
- RF/Microwave Innovations Part I & II
- Counterfeit Prevention & Mitigation Strategies
- Wire Bonding & Advanced Interconnections
- 2.5/3D Packaging Technologies & Methods
- Bumped Die Attach

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Key Presenters

With the support of many well-known authors and their companies, you will find many technical tracks that peak your interest and strengthen your knowledge. Here's a sampling of the companies that will present their technical expertise:

- Lockheed Martin
- NXP Semiconductors
- MIT/Brookhaven Labs
- Fairchild
- DuPont
- Cree
- Raytheon
- NAMICS
- IBM

For a detailed look at all authors, sessions, paper titles and other participating leading-edge companies, [click here](#).

Program Information and Registration Links

- [Technical Program Overview](#)
- [Symposium Information and Registration](#)
- Special Symposium Hotel Rate at Holiday Inn—[register online](#) or call 1-800-Holiday and use group code MAP.
- RF Microwave Packaging Technology Class, May 7-9 with TJ Green Associates and iMAPS New England Course: [Register online](#)

Exhibitor, Sponsor and General Information Contacts

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